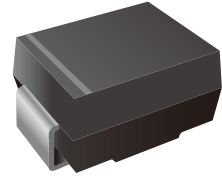


Surface Mount Schottky Barrier Rectifier

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case: SMB
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end

Ordering Information

Part Number	Marking	Shipping	Reel
LT5B40-TR3	5B40 or SSL54	3000PCS Tape&Reel	13 inches

Maximum Ratings and Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbol	LT5B40	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	V
Maximum RMS voltage	V_{RMS}	28	V
Maximum DC Blocking Voltage	V_{DC}	40	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	150	A
Max Instantaneous Forward Voltage at 5 A	V_F	0.45	V
Maximum DC Reverse Current at Rated DC Reverse Voltage	I_R	1 50	mA
Typical Junction Capacitance (Note1)	C_j	320	pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	45	°C/W
Operating Junction Temperature Range	T_j	-55 to +125	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C

Note: (1) Measured at 1 MHz and applied reverse voltage of 4V D.C.

(2) P.C.B. mounted with 2.0" x 2.0" (5cm x 5cm) copper pad areas.



Characteristics Curves

Fig.1 Forward Current Derating Curve

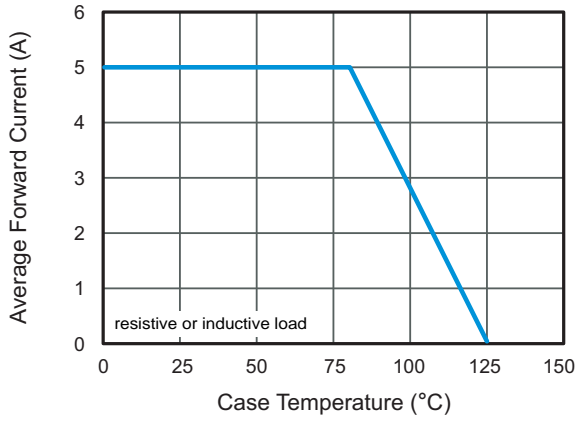


Fig.2 Typical Reverse Characteristics

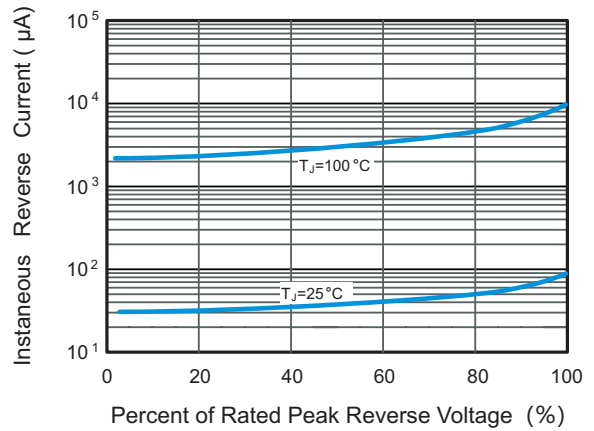


Fig.3 Typical Forward Characteristic

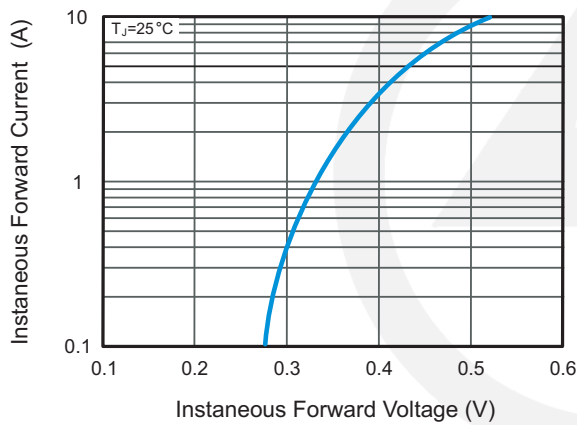


Fig.4 Typical Junction Capacitance

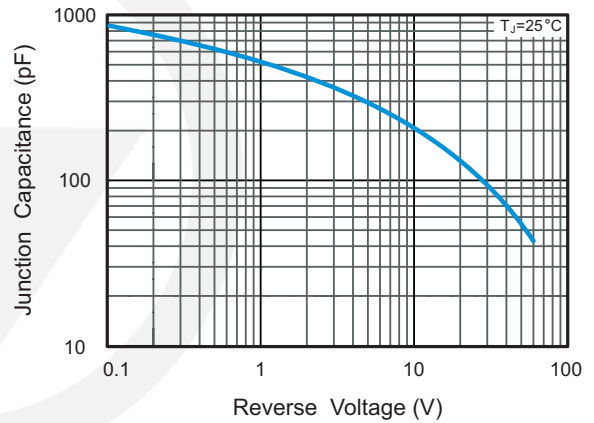
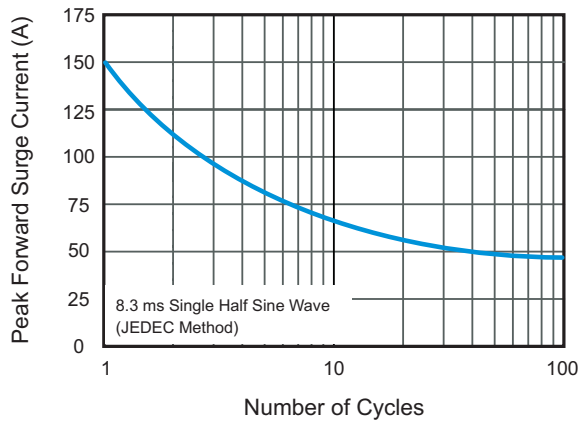
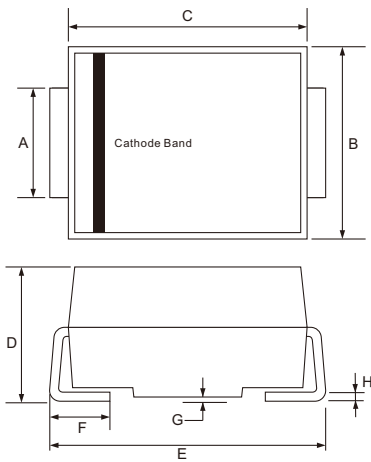


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



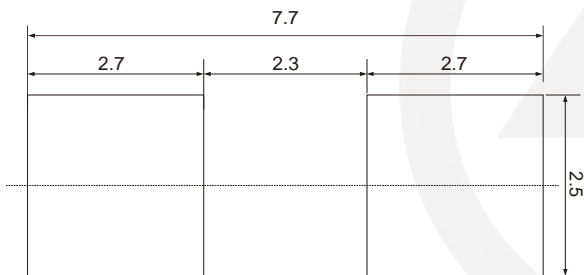
SMB Package Outline



Unit: mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.90	2.20
B	3.30	3.94
C	4.05	4.75
D	2.13	2.65
E	5.08	5.59
F	0.76	1.52
G	0.203 TYP.	
H	0.15	0.31

SMB Suggested Pad Layout

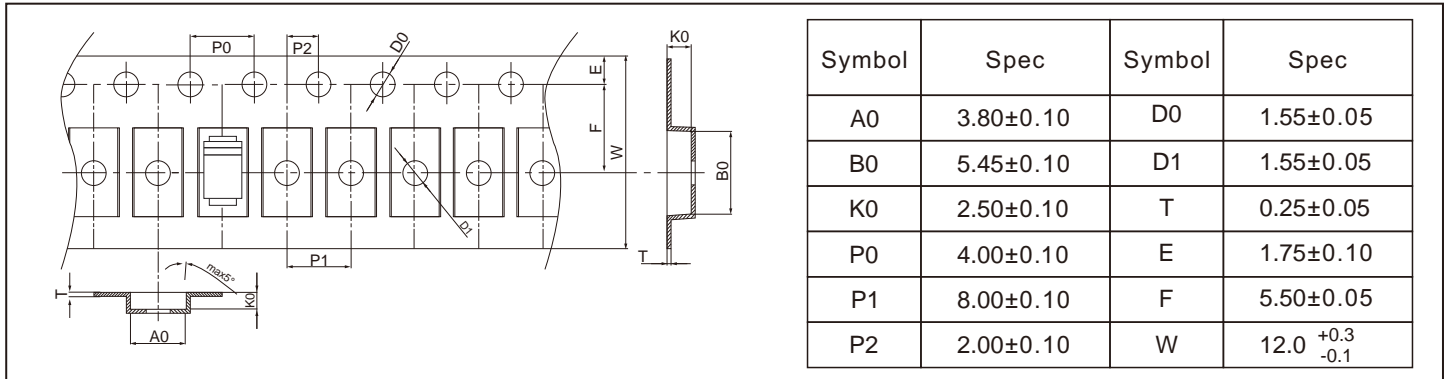


Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

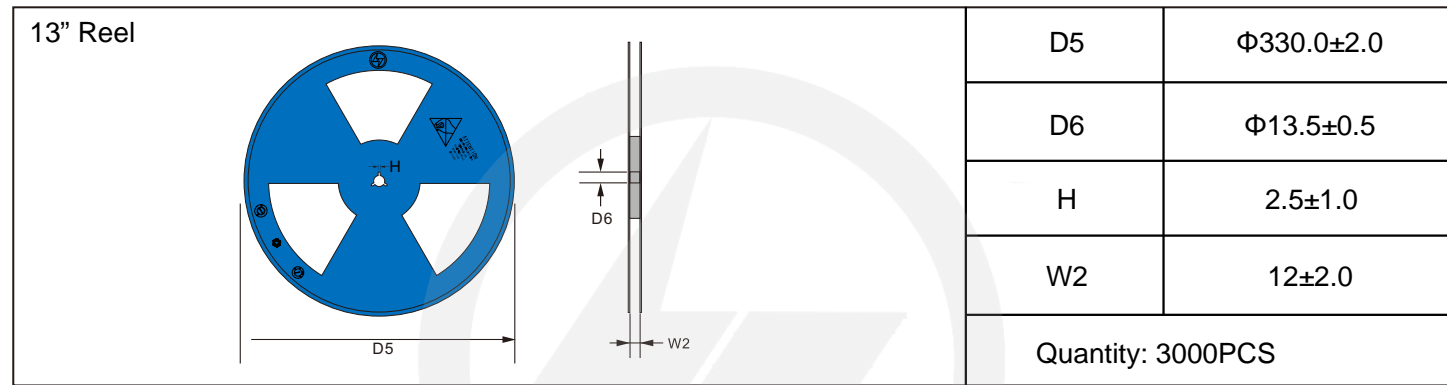
Carrier Tape Dimensions

Unit : mm

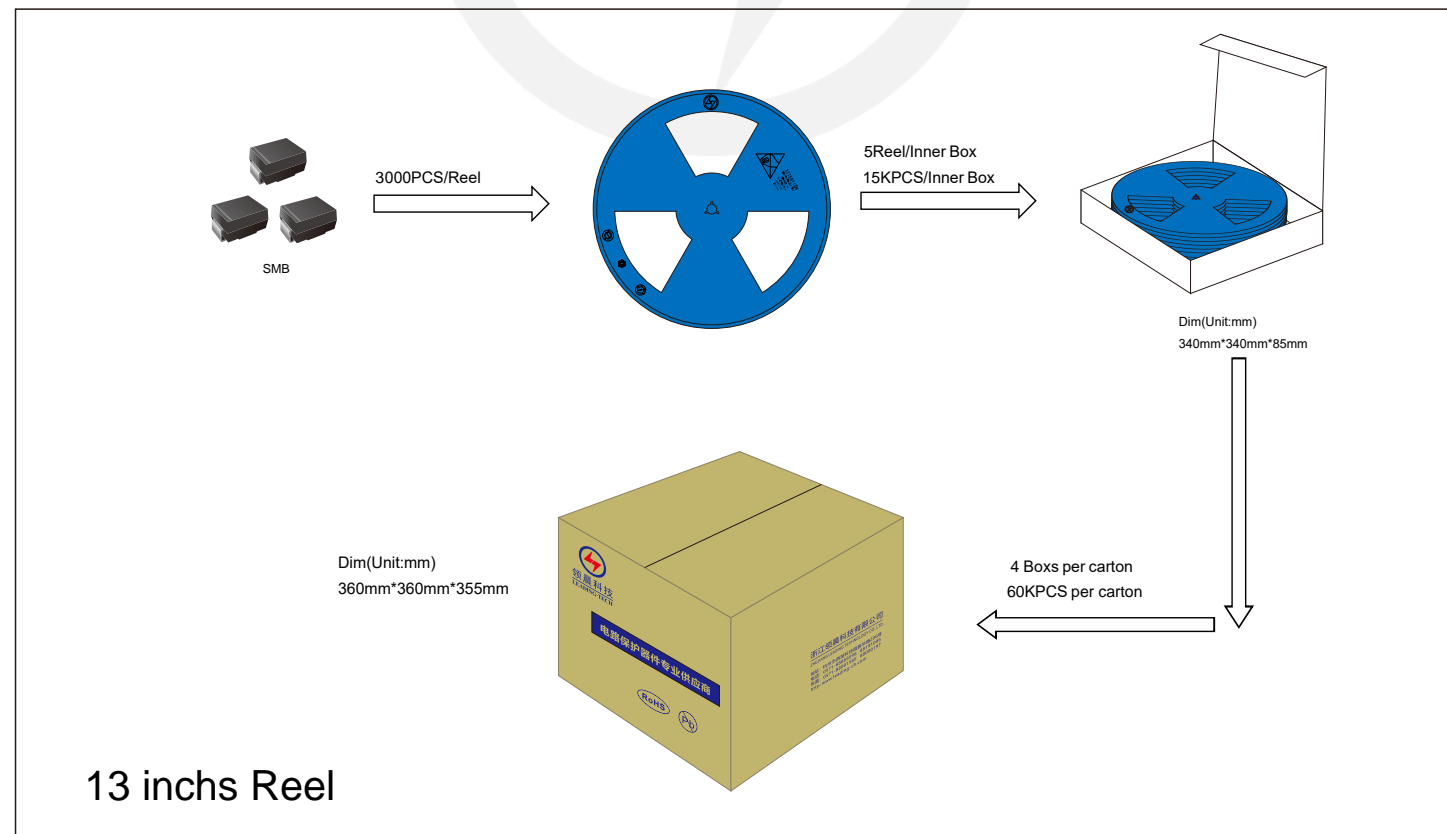


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat	
-Temperature Min ($T_{S\ min}$)	150°C
-Temperature Max ($T_{S\ max}$)	200°C
-Time (min to max) (t_s)	60-180 seconds
$T_{S\ max}$ to T_L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2024.3.18	2024.3.18	3.0	New File	/	Ding	
02	2025.06.12	2025.06.12	3.1	Update packaging information	/	Ding	